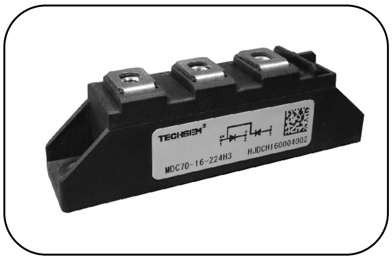


Features：

- Isolated mounting base 3000V~
- Solder joint technology with increased power cycling capability
- Space and weight saving

Typical Applications：

- Various rectifiers
- DC supply for PWM inverter

V_{RRM}	Type & Outline
600V	MDC55-06-224H3
800V	MDC55-08-224H3
1000V	MDC55-10-224H3
1200V	MDC55-12-224H3
1400V	MDC55-14-224H3
1600V	MDC55-16-224H3
1800V	MDC55-18-224H3

SYMBOL	CHARACTERISTIC	TEST CONDITIONS	T_j(°C)	VALUE			UNIT
				Min	Type	Max	
$I_{F(AV)}$	Mean forward current	180° half sine wave 50Hz Single side cooled, T_C=100°C	150			55	A
$I_{F(RMS)}$	RMS forward current		150			86	A
I_{RRM}	Repetitive peak current	at V_{RRM}	150			8	mA
I_{FSM}	Surge forward current	10ms half sine wave V_R=0.6V_{RRM}	150			1.8	kA
I^2t	I^2t for fusing coordination					16.2	10^3A^2s
V_{FO}	Threshold voltage		150			0.80	V
r_F	Forward slope resistance					3.74	mΩ
V_{FM}	Peak forward voltage	I_{FM}=170A	25			1.40	V
$R_{th(j-c)}$	Thermal resistance Junction to case	Single side cooled per chip				0.70	°C /W
$R_{th(c-h)}$	Thermal resistance case to heatsink	Single side cooled per chip				0.20	°C /W
V_{iso}	Isolation voltage	50Hz, R.M.S,t=1min, I_{iso}:1mA(max)		3000			V
F_m	Terminal connection torque(M5)			2.5		4.0	N·m
	Mounting torque(M6)			4.5		6.0	N·m
T_{vj}	Junction temperature			-40		150	°C
T_{stg}	Stored temperature			-40		125	°C
W_t	Weight				100		g
Outline	224H3						

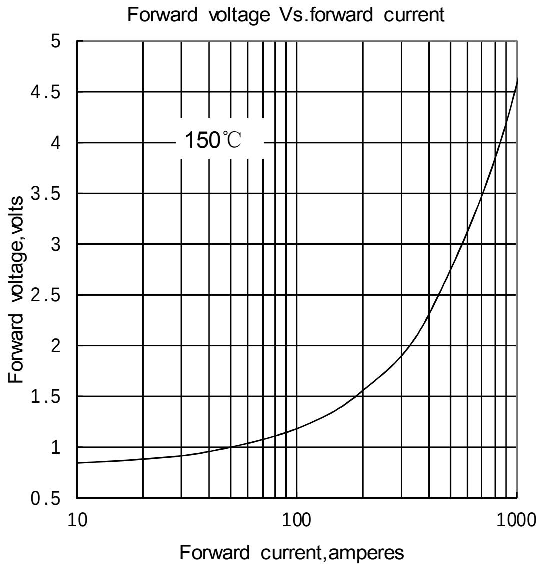


Fig.1

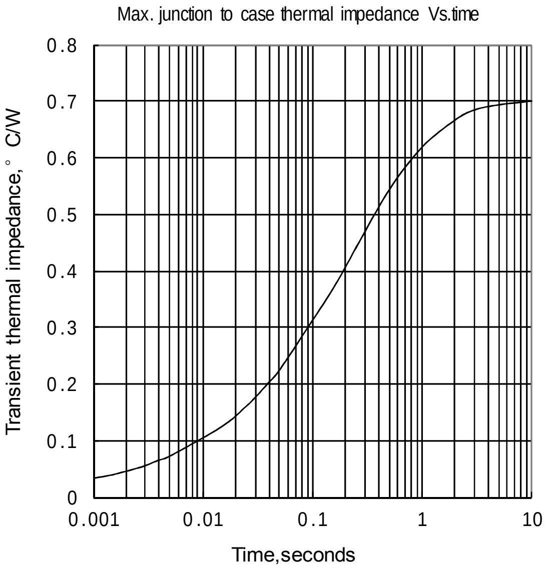


Fig.2

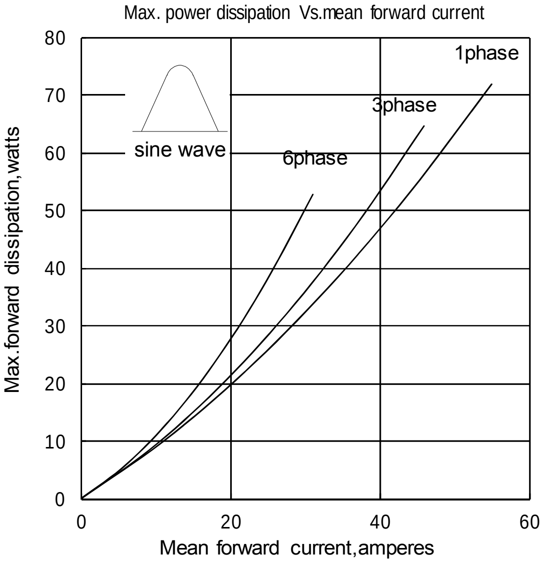


Fig.3

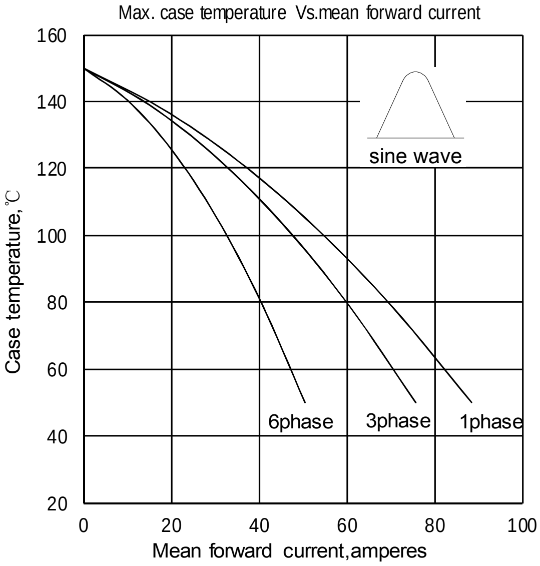


Fig.4

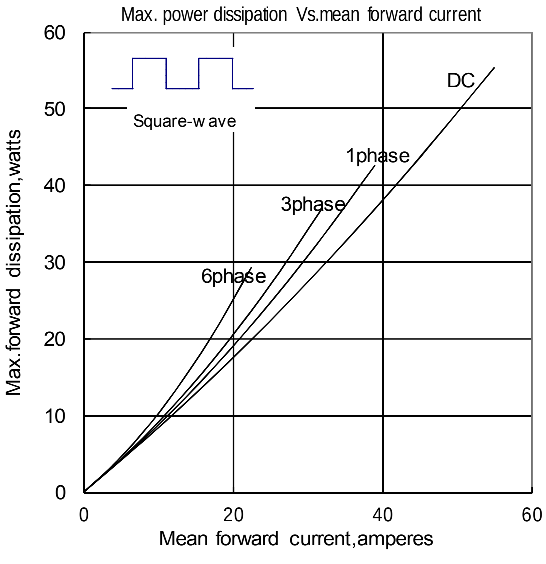


Fig.5

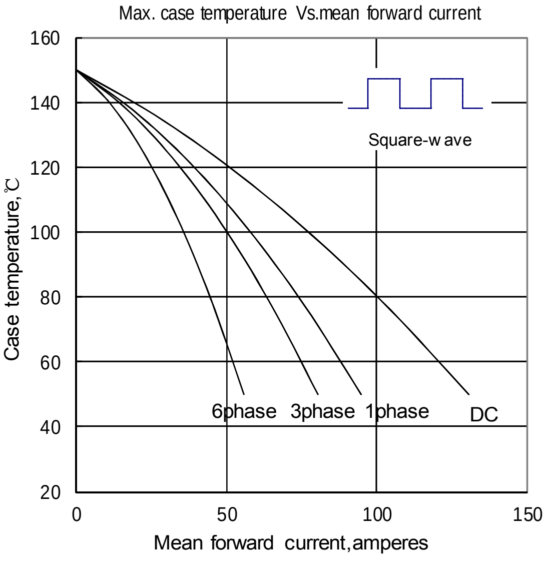


Fig.6

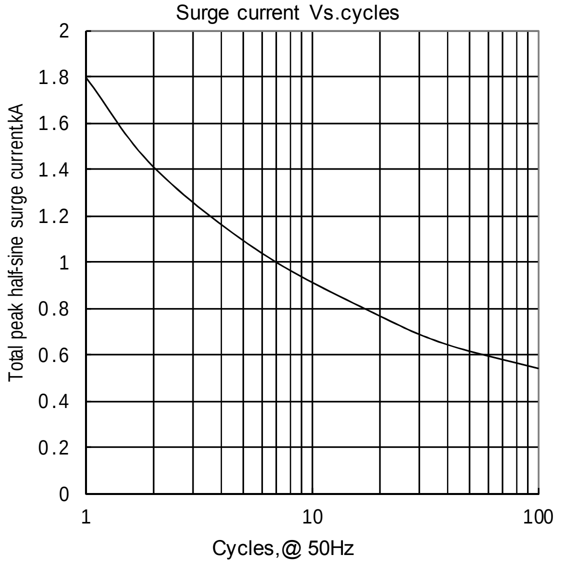


Fig.7

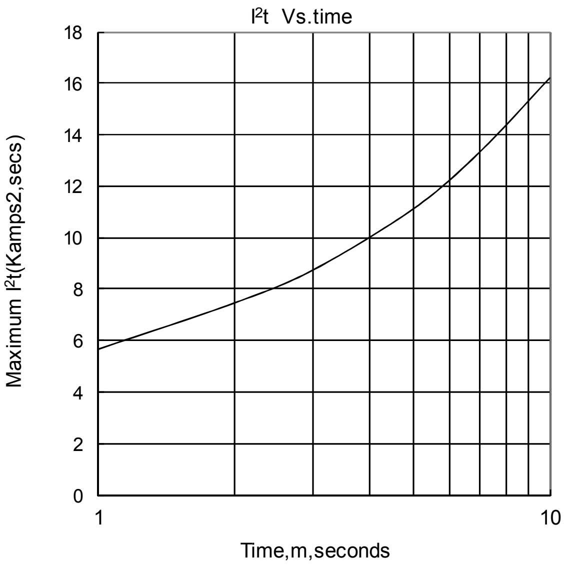
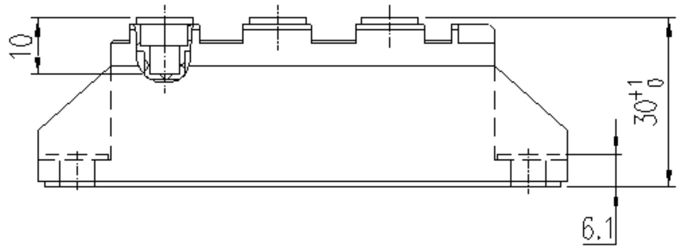
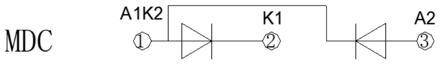
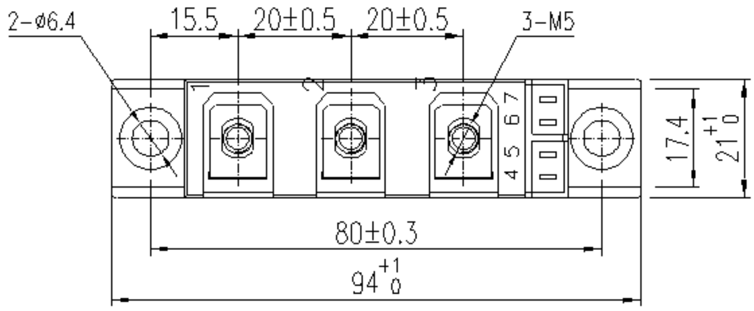


Fig.8

Outline:







Unmarked dimensional tolerance：±0.5mm